

FCD5N60TM Datasheet



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DiGi Electronics Part Number FCD5N60TM-DG

Manufacturer onsemi

Manufacturer Product Number FCD5N60TM

Description MOSFET N-CH 600V 4.6A DPAK

Detailed Description N-Channel 600 V 4.6A (Tc) 54W (Tc) Surface Mount

TO-252AA



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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
FCD5N60TM	onsemi
Series:	Product Status:
SuperFET™	Not For New Designs
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
600 V	4.6A (Tc)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
10V	950m0hm @ 2.3A, 10V
Vgs(th) (Max) @ ld:	Gate Charge (Qg) (Max) @ Vgs:
5V @ 250μA	16 nC @ 10 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±30V	600 pF @ 25 V
FET Feature:	Power Dissipation (Max):
	54W (Tc)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Surface Mount
Supplier Device Package:	Package / Case:
TO-252AA	TO-252-3, DPAK (2 Leads + Tab), SC-63
Base Product Number:	
ECDENIA	

Environmental & Export classification

8541.29.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	



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August 2014

FCD5N60 / FCU5N60 N-Channel SuperFET MOSFET 600 V, 4.6 A, 950 m Ω

Features

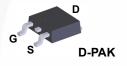
- 650 V @ T_J = 150°C
- Typ. $R_{DS(on)}$ = 810 m Ω
- Ultra Low Gate Charge (Typ. Q_q = 16 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 32 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

Application

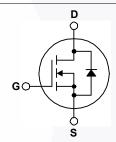
- · LCD/LED TV and Monitor
- Lighting
- · Solar Inverter
- AC-DC Power Supply

Description

SuperFET® MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.







MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FCD5N60TM FCD5N60TM_WS FCU5N60TU	Unit	
V _{DSS}	Drain to Source Voltage		600	V	
	Drain Current	- Continuous (T _C = 25°C)		^	
ID	Drain Current	- Continuous (T _C = 100°C)	2.9	Α	
I _{DM}	Drain Current	- Pulsed (Note 1)	13.8	Α	
V _{GSS}	Gate to Source Voltage		±30	V	
E _{AS}	Single Pulsed Avalanche Er	nergy (Note 2)	159	mJ	
I _{AR}	Avalanche Current	(Note 1)	4.6	Α	
E _{AR}	Repetitive Avalanche Energ	y (Note 1)	5.4	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns	
n	Dawer Dissipation	(T _C = 25°C)	54	W	
P_{D}	Power Dissipation	- Derate Above 25°C	0.43	W/°C	
T _J , T _{STG}	Operating and Storage Tem	perature Range	-55 to +150	οС	
T _L	Maximum Lead Temperatur	e for Soldering, 1/8" from Case for 5 Seconds	300	οС	

Thermal Characteristics

Symbol	Parameter	FCD5N60TM FCD5N60TM_WS FCU5N60TU	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	2.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	83	C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCD5N60TM	FCD5N60	D-PAK	Tape and Reel	330 mm	16 mm	2500 units
FCD5N60TM_WS	FCD5N60	D-PAK	Tape and Reel	330 mm	16 mm	2500 units
FCU5N60TU	FCU5N60	IPAK	Tube	N/A	N/A	75 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
D\/	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}, T_C = 25^{\circ}\text{C}$	600	-	-	V
BV _{DSS}	V _{DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}, T_C = 150^{\circ}\text{C}$	-	650	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	-	0.6	-	V/°C
BV _{DS}	Drain to Source Avalanche Breakdown Voltage	V _{GS} = 0 V, I _D = 4.6 A	-	700	-	V
1	Zero Gate Voltage Drain Current	V _{DS} = 600 V, V _{GS} = 0 V	-	-	1	
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 480 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	10	μΑ
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 2.3 \text{ A}$	-	0.81	0.95	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_{D} = 2.3 \text{ A}$	-\	3.8	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz V _{DS} = 480 V, V _{GS} = 0 V, f = 1 MHz	-	470	600	pF
C _{oss}	Output Capacitance		-	250	320	pF
C _{rss}	Reverse Transfer Capacitance		-	22	-	pF
C _{oss}	Output Capacitance		-	12	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	32	-	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		- /	12	30	ns
t _r	Turn-On Rise Time	$V_{DD} = 300 \text{ V}, I_D = 4.6 \text{ A},$	-	40	90	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{G} = 25 Ω	/-	47	95	ns
t _f	Turn-Off Fall Time	(Note 4	-	22	55	ns
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 480 V, I _D = 4.6 A,	-	16	-	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	2.8	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4	_	7	_	nC

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current		-	4.6	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	13.8	Α
V_{SD}	Drain to Source Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_{SD} = 0 \text{ V}$	4.6 A -	-	1.4	V
t _{rr}	Reverse Recovery Time $V_{GS} = 0 \text{ V, } I_{SD} = 0 \text{ V}$	4.6 A	295	-	ns
Q_{rr}	Reverse Recovery Time $V_{GS} = 0 \text{ V, } I_{SD} = 0 \text{ Reverse Recovery Charge}$ Reverse Recovery Charge $dI_F/dt = 100 \text{ A/}\mu\text{s}$	-	2.7	-	μС

Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. I_{AS} = 2.3 A, V_{DD} = 50 V, R_G = 25 Ω , starting T_J = 25°C.
- 3. I $_{SD}$ \leq 4.6 A, di/dt \leq 200 A/µs, V $_{DD}$ \leq BV $_{DSS}$, starting T $_{J}$ = 25°C.
- ${\bf 4.} \ {\bf Essentially independent \ of \ operating \ temperature \ typical \ characteristics.}$

Typical Performance Characteristics

Figure 1. On-Region Characteristics

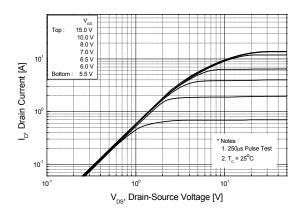


Figure 2. Transfer Characteristics

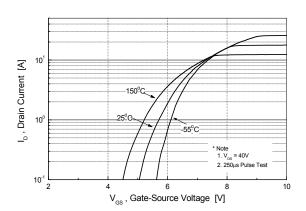
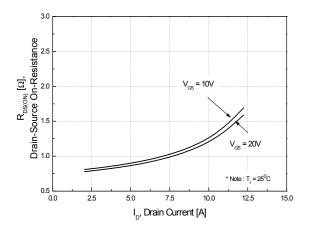


Figure 3. On-Resistance Variation vs. **Drain Current and Gate Voltage**

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue



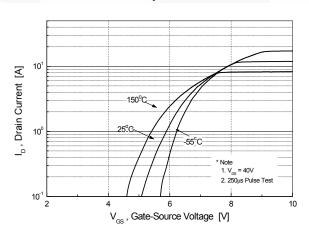


Figure 5. Capacitance Characteristics

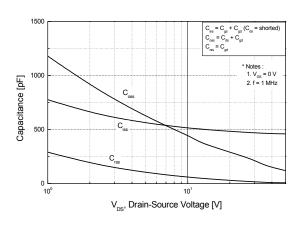
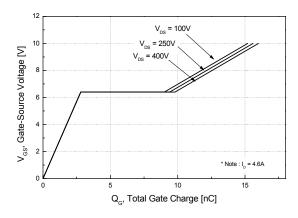


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

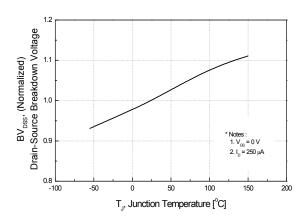


Figure 8. On-Resistance Variation vs. Temperature

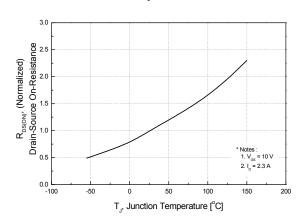


Figure 9. Maximum Safe Operating Area

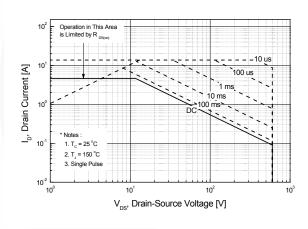


Figure 10. Maximum Drain Current vs. Case Temperature

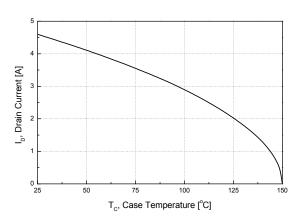
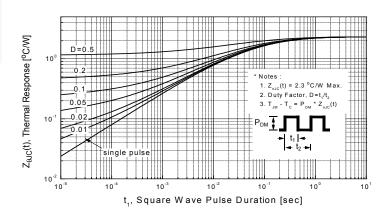


Figure 11. Transient Thermal Response Curve



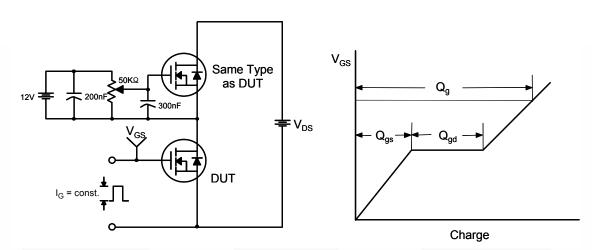


Figure 12. Gate Charge Test Circuit & Waveform

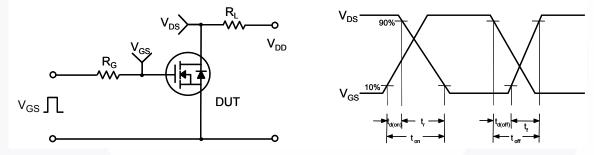


Figure 13. Resistive Switching Test Circuit & Waveforms

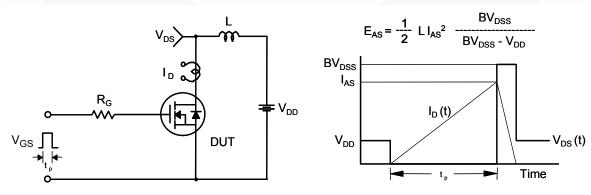


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

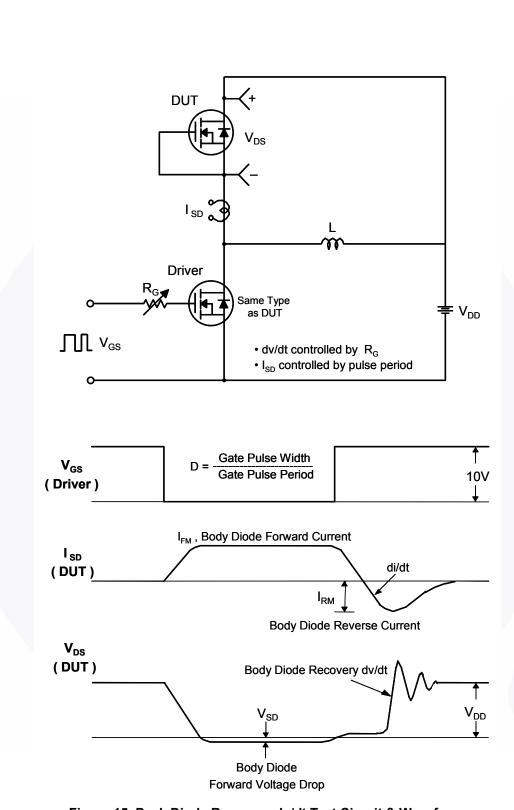


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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